

12-26-96

01-05-2007



IN THE U.S.

103357168

ADEMARK OFFICE

113268 U.S. PTO
11/645488
122606

Applicant: Charles W.C. Lin et al.
Assignee: Bridge Semiconductor Corporation
Title: METHOD OF MAKING A SEMICONDUCTOR CHIP
ASSEMBLY WITH THERMAL CONDUCTOR AND
ENCAPSULANT GRINDING
Serial No.: Unknown Filed: Herewith
Examiner: Unknown Group Art Unit: Unknown
Atty. Docket No.: BDG045

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

ASSIGNMENT RECORDATION COVER SHEET

Dear Sir:

Please record the attached original Assignment.

1. Name of conveying parties:

Charles W.C. Lin
Chia-Chung Wang

2. Name and address of receiving party:

Bridge Semiconductor Corporation
3rd Floor, 157 Li-Te Road
Peitou District
Taipei, Taiwan 112

3. Nature of conveyance:

Assignment

The execution date of the Assignment is December 20, 2006.

4. Application number(s) or patent number(s)

This Assignment is being filed together with a new patent application. The execution date of the application is December 20, 2006.

5. Name and address of party to whom correspondence should be mailed:

David M. Sigmond
487 Blackfoot Street
Superior, Colorado 80027

(303) 554-8371

6. Total number of applications and patents involved: 1.

7. Total fee under 37 C.F.R. § 1.21(h): \$40.

8. Method of Payment:

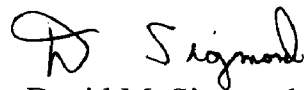
Charge the \$40 to Deposit Account No. 502178/BDG045 and charge any underpayment or credit any overpayment to this Account.

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Total number of pages including cover sheet, attachments and document: 4.

Respectfully submitted,



David M. Sigmond
Attorney for Applicant
Reg. No. 34,013
(303) 554-8371
(303) 554-8667 (fax)

Date: 12 / 26 / 06

01/04/2007 NJANA1 00000052 502178 11645488
01 FC:8021 40.00 DA


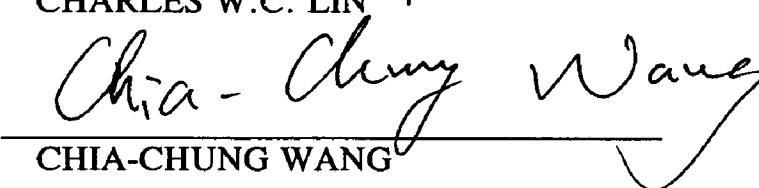
ASSIGNMENT

WHEREAS, we, CHARLES W.C. LIN of Singapore, and CHIA-CHUNG WANG of Taiwan, have invented a certain new and useful invention entitled METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH THERMAL CONDUCTOR AND ENCAPSULANT GRINDING, for which an application for Letters Patent of the United States has been prepared for filing, said application being identified as Attorney Docket No. BDG045;

NOW THEREFORE, be it known that we, the said inventors, for and in consideration of certain good and valuable consideration, the sufficiency and receipt of which is hereby acknowledged, at the request of the assignee do sell, assign and transfer unto said assignee, BRIDGE SEMICONDUCTOR CORPORATION, a Taiwan Corporation having a place of business at 3rd Floor, 157 Li-Te Road, Peitou District, Taipei, Taiwan 112, its successors, legal representatives and assigns, the aforesaid application for the territory of the United States of America and all continuation, divisional, continuation-in-part and reissue applications, all patent applications in foreign countries, all applications pursuant to the Patent Cooperation Treaty, and all applications for extension filed or to be filed for the invention, and all Letters Patent, Invention Registrations, Utility Models, Extensions or Reissues, Reexaminations and other patent rights, obtained for the invention in the United States or any other country; we also assign any right, title or interest in and to the invention which has not already been transferred to the assignee; we warrant that we have made no assignment of the invention, application or patent therefor to a party other than BRIDGE SEMICONDUCTOR CORPORATION and we are under no obligation to make and shall not make any assignment of the invention, application, or patent therefor to any other party; and we further agree to cooperate with the assignee hereunder in obtaining, sustaining and enforcing of any and all such Letters Patent and patent rights and in confirming the assignee's exclusive ownership of the invention, without further consideration, but at the expense of said assignee.

The Commissioner of Patents is hereby authorized and requested to issue the Letters Patent solely in accordance with the terms of this Assignment to BRIDGE SEMICONDUCTOR CORPORATION, its successors, legal representatives and assigns, as the assignee of the entire right, title and interest therein.

IN WITNESS WHEREOF, the parties hereto have executed this Assignment as of the date indicated hereunder.

Date: <u>Dec. 20, 2006</u>	By:  CHARLES W.C. LIN
Date: <u>Dec. 20, 2006.</u>	By:  CHIA-CHUNG WANG

NOTARY JURISDICTION: _____

Before me, a Notary Public in and for said Notary Jurisdiction, personally appeared CHARLES W.C. LIN, known to me to be the person whose name is subscribed to the foregoing instrument, and acknowledged to me that he executed the same for the purposes and considerations therein expressed.

Given under my hand and seal of office this _____ day of _____, 2006.

095 士院認 003

案號 : 002616	日期 : DEC 20 2006
Case No. 002616	Date: DEC 20 2006
本文件 林力強 之簽名或蓋章，在台灣士林地方法院公證處認證。	
公證人 城素芬	
Attested at the Notary Public Office of Taiwan Shiblin District Court, R.O.C. that the signature(s)/seal(s) of CHARLES W.C. LIN in this document is/are authentic.	
Notary Public	
Chen, Sue-Feng	

Notary Public

My Commission Expires: _____

NOTARY JURISDICTION: _____

Before me, a Notary Public in and for said Notary Jurisdiction, personally appeared CHIA-CHUNG WANG, known to me to be the person whose name is subscribed to the foregoing instrument, and acknowledged to me that he executed the same for the purposes and considerations therein expressed.

Given under my hand and seal of office this _____ day of _____, 2006.

Notary Public

My Commission Expires: _____